

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	83	(US-20020142513-\$).did. or (US-5108955-\$ or US-5147815-\$ or US-5147821-\$ or US-5215639-\$ or US-5266834-\$ or US-5395226-\$ or US-5422163-\$ or US-5424249-\$ or US-5424251-\$ or US-5444025-\$ or US-5450283-\$ or US-5474958-\$ or US-5604376-\$ or US-5609889-\$ or US-5654584-\$ or US-5656549-\$ or US-5679978-\$ or US-5694366-\$ or US-5733802-\$ or US-5750423-\$ or US-5766649-\$ or US-5766650-\$ or US-5776800-\$ or US-5800841-\$ or US-5811877-\$ or US-5817545-\$).did. or (US-5891384-\$ or US-5891483-\$ or US-5903504-\$ or US-5923959-\$ or US-6000924-\$ or US-6019588-\$ or US-6033933-\$ or US-6048483-\$ or US-6069408-\$ or US-6081978-\$ or US-6081997-\$ or US-6117382-\$ or US-6123895-\$ or US-6187243-\$ or US-6224360-\$ or US-6284565-\$ or US-6306331-\$ or US-6329224-\$ or US-6332766-\$ or US-6344162-\$ or US-6350113-\$ or US-6383846-\$ or US-6397465-\$ or US-6413801-\$ or US-6420783-\$ or US-6428300-\$ or US-6472252-\$).did. or (US-6501184-\$ or US-6525406-\$ or US-6534338-\$ or US-6537853-\$ or US-6558980-\$ or US-6558982-\$ or US-6952046-\$ or US-6350631-\$ or US-6656773-\$ or US-6664139-\$ or US-6683388-\$ or US-6767767-\$ or US-5998243-\$ or US-5981312-\$ or US-5834340-\$ or US-5077237-\$ or US-6863516-\$ or US-6838319-\$ or US-6632704-\$ or US-5710062-\$ or US-5672550-\$ or US-6817854-\$ or US-6712594-\$ or US-6555924-\$).did. or (JP-10138294-\$ or JP-2000195883-\$).did. or (JP-06302636-\$ or JP-08142106-\$ or US-6284566-\$).did.	US-PGPUB; USPAT; JPO; DERWENT	OR	ON	2005/10/05 10:22
L2	8127	seal\$3 with (graphite kalrez\$1)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/05 13:32

L3	232	L2 with mold	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/05 10:52
L4	13	L3 and semiconductor	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/05 13:34
L5	3	L2 with ((upper lower) near mold)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/05 13:33
L6	9167	(seal\$3 gasket) with (graphite kalrez\$1)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/05 10:53
L7	6	6 with ((upper lower) near mold)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/05 10:54
L8	488	kalrez\$1	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/05 13:32
L9	185	8 with (seal\$3 gasket)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/05 13:54
L10	0	9 same ((upper lower) near mold)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/05 13:55

L11	0	9 and ((upper lower) near mold)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/05 13:33
L12	5	9 same semiconductor	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/05 13:58
L13	67	9 and semiconductor	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/05 13:54
L14	201464	graphite	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/05 13:54
L15	8985	14 with (seal\$3 gasket)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/05 14:08
L16	9	15 same ((upper lower) near mold)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/05 13:55
L17	125	15 same semiconductor	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/05 14:08
L18	4310	14 near4 (seal\$3 gasket)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/05 14:08

L19	3459	14 near3 (seal\$3 gasket)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/05 14:08
L20	39	19 same semiconductor	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/05 14:08